

Discription

The HSZESD9101P2T5G protects sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events. Excellent clamping capability, low leakage, low capacitance, and fast response time provide best in class protection on designs that are exposed to ESD.

It gives designer the flexibility to protect one unidirectional line in applications where arrays are not practical.

Features

- ★ Ultra Low Capacitance 0.35 pF
- ★ Low Clamping Voltage
- ★ Small Body Outline Dimensions: 0.031" x 0.024" (0.80 mm x 0.60 mm)
- ★ Low Body Height: 0.015" (0.37 mm)
- ★ Stand-off Voltage: 5 V
- ★ Low Leakage
- ★ Response Time is Typically < 1.0 ns
- ★ IEC61000-4-2 Level 4 ESD Protection
- ★ This is a Pb-Free Device

Orderingin formation

SOD-923



Circuit Diagram

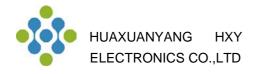
| Product ID | Pack | Qty(PCS) | |
|-----------------|---------|----------|--|
| HSZESD9101P2T5G | SOD-923 | 8000 | |

Absolute Ratings(Tamb = 25°C)

| Symbol | Parameter | Value | Units |
|------------------|--|-------------|-------|
| P _{PP} | Peak Pulse Power (t _P = 8/20µs) | 60 | W |
| TL | Maximum lead temperature for soldering during 10s | 260 | °C |
| T _{stg} | Storage Temperature Range | -55 to +150 | °C |
| T _{op} | Junction Temperature Range | -55 to +125 | °C |
| Tj | Maximum junction temperature | 150 | °C |
| | IEC61000-4-2 (ESD) air discharge contact discharge | | KV |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. FR-5 = 1.0 x 0.75 x 0.62 in.



Electrical Characteristics (T_A = 25°C unless otherwise noted, V_F = 1.0 V Max. @ I_F = 10 mA for all types)

| Device | V _{RWM} (V) | I _R (μΑ) @ V _{RWM} | V _{BR} (V) @ I _T (Note 2) | г | C (pF) | V _C (V) @ I _{PP} = 1 A (Note 3) | lpp (A) | Ppk (W) (8*20 µS) | vc |
|-----------------|-------------------------|---|--|-----|--------|---|------------|-------------------------|------------------------------|
| | Max | Max | Min | mA | Тур | Max | Max | Мах | Per IEC61000-4-2 (Note 4) |
| HSZESD9101P2T5G | 5.0 | 1.0 | 5.4 | 1.0 | 0.5 | 15 | 4 | 60 | Figures 1 and 2 See Below |

2. V_{BR} is measured with a pulse test current I_T at an ambient temperature of 25°C. 3. Surge current waveform per Figure 5.

4. For test procedure see Figures 3 and 4.

Typical Characteristics

IEC 61000-4-2 Spec.

| Level | Test Voltage (kV) | First Peak Current (A) | Current at 30 ns (A) | Current at 60 ns (A) |
|-------|-------------------------|------------------------------|-------------------------|-------------------------|
| 1 | 2 | 7.5 | 4 | 2 |
| 2 | 4 | 15 | 8 | 4 |
| 3 | 6 | 22.5 | 12 | 6 |
| 4 | 8 | 30 | 16 | 8 |

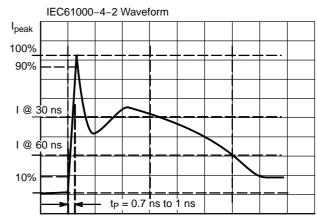
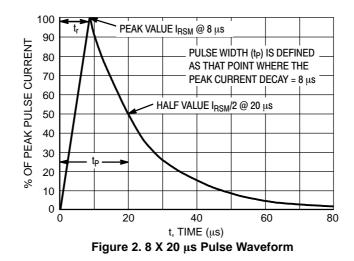
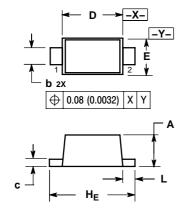


Figure 1. IEC61000-4-2 Spec





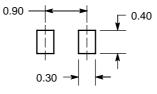
SOD-923 Outline And Dimensions



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

| | MIL | LIMETE | RS | INCHES | | | |
|----------------|------|--------|------|--------|-------|-------|--|
| DIM | MIN | NOM | MAX | MIN | NOM | MAX | |
| Α | 0.34 | 0.37 | 0.40 | 0.013 | 0.015 | 0.016 | |
| b | 0.15 | 0.20 | 0.25 | 0.006 | 0.008 | 0.010 | |
| С | 0.07 | 0.12 | 0.17 | 0.003 | 0.005 | 0.007 | |
| D | 0.75 | 0.80 | 0.85 | 0.030 | 0.031 | 0.033 | |
| E | 0.55 | 0.60 | 0.65 | 0.022 | 0.024 | 0.026 | |
| H _E | 0.95 | 1.00 | 1.05 | 0.037 | 0.039 | 0.041 | |
| L | 0.05 | 0.10 | 0.15 | 0.002 | 0.004 | 0.006 | |

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS



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